

# AN11044

Pin FMEA for 74HC/74HCT family

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Application note

## Document information

Info	Content
<b>Keywords</b>	FMEA, HC, HCT, CMOS
<b>Abstract</b>	This application note provides a Failure Modes and Effects Analysis (FMEA) for the NXP Semiconductors' 74 HC/74HCT family under typical failure situations.



## Revision history

Rev	Date	Description
v.1	20110316	initial version

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## 1. Introduction

The 74HC/74HCT high-speed Si-gate CMOS logic family combines the low power advantages of the HEF4000B family with the high speed and drive capability of the Low power Schottky TTL (LSTTL).

The 74HC/74HCT family has the same pin-out as the 74 series and provides the same circuit functions. The family includes several HEF4000B family circuits that do not have TTL counterparts, and have some special circuits. The basic family of buffered devices, designated as xx74HCxxxx, operates at CMOS input logic levels for high-noise immunity with negligible typical quiescent supply and input current. The family requires a power supply of 2 V to 6 V. A subset of the family, designated as xx74HCTxxxx with the same features as the "HC-types" will operate with a standard TTL power supply of 5 V ( $\pm 10\%$ ) and logic input levels (0.8 V to 2.0 V) for use as pin-to-pin compatible CMOS replacements for reducing power consumption without loss of speed. These types are also suitable for TTL-to-CMOS switching converters.

## 2. Pin FMEA

This application note provides a Failure Modes and Effects Analysis (FMEA) for the NXP Semiconductors' HC/HCT family under typical failure situations such as a short-circuit of HC/HCT device pins to  $V_{CC}$  or GND or to a neighboring pin, or if a pin is left open. A failure is classified according to its effect on the HC/HCT device and the functionality of the application; see [Table 1](#).

**Table 1. Classification of failure effects**

Class	Failure effect
A	damage to device affects application functionality
B	no damage to device may affect application functionality
C	no damage to device no affect to application functionality

**Table 2. FMEA matrix for pin short-circuit to  $V_{CC}$**

Pin	Class	Remarks
Input	B	normal operating condition, no damage, no leakage, may affect functionality
Output	C	if output defined HIGH, no damage, no leakage, no output level change
Output	A	if output defined LOW, short-circuits and high currents can damage device, output level changes
GND	B	short-circuits and high currents can damage device, affects functionality

**Table 3. FMEA matrix for pin short-circuit to GND**

Pin	Class	Remarks
Input	B	normal operating condition, no damage, no leakage; may affect functionality
Output	C	if output defined LOW, no damage, no leakage no output level change
Output	A	if output defined HIGH, short-circuits and high currents can damage device, output level changes
V <sub>CC</sub>	B	if input defined LOW, no damage, affects functionality
V <sub>CC</sub>	A	if input defined HIGH, short-circuits and high currents can damage device, affects functionality

**Table 4. FMEA matrix for pin left open**

Pin	Class	Remarks
Input	B	undefined operating condition, no damage, increases leakage, may affect functionality
Output	C	normal operating condition, no damage, no leakage
GND	B	undefined operating condition, no damage, increases leakage, affects functionality
V <sub>CC</sub>	B	if input defined LOW, undefined operating condition, no damage, increases leakage (only for I/O types), affects functionality
V <sub>CC</sub>	B	if input defined HIGH, device is powered via input circuit, may affect functionality

**Table 5. FMEA matrix for pin short-circuits between neighbor pins**

Pin	Class	Remarks
Input to input	C	if inputs have same voltage levels: no damage, no leakage
	B	if inputs have different voltage levels: leakage increases, affects functionality
Input to output	A	if input and output have different voltage levels, can cause high current and can damage device, affects functionality
	C	if input and output have same voltage levels, no damage, no leakage
Input to GND	-	see <a href="#">Table 3</a>
Input to V <sub>CC</sub>	-	see <a href="#">Table 2</a>
Output to output	C	if outputs have same voltage levels, no damage, no leakage
	A	if outputs have different voltage levels, can cause high current and can damage device, affects functionality
Output to input	-	same effect as 'input to output' condition
Output to GND	-	see <a href="#">Table 3</a>
Output to V <sub>CC</sub>	-	see <a href="#">Table 2</a>
GND to V <sub>CC</sub>	-	not applicable, these pins are not neighbors

### 3. Abbreviations

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**Table 6. Abbreviations**

<b>Acronym</b>	<b>Description</b>
CMOS	Complementary Metal-Oxide Semiconductor
FMEA	Failure Modes and Effects Analysis
LSTTL	Low power Schottky TTL
TTL	Transistor-Transistor Logic

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